SOLID STATE OPTRONICS



SDD600

DC Input
300V
Photo-Darlington Optocoupler

Description

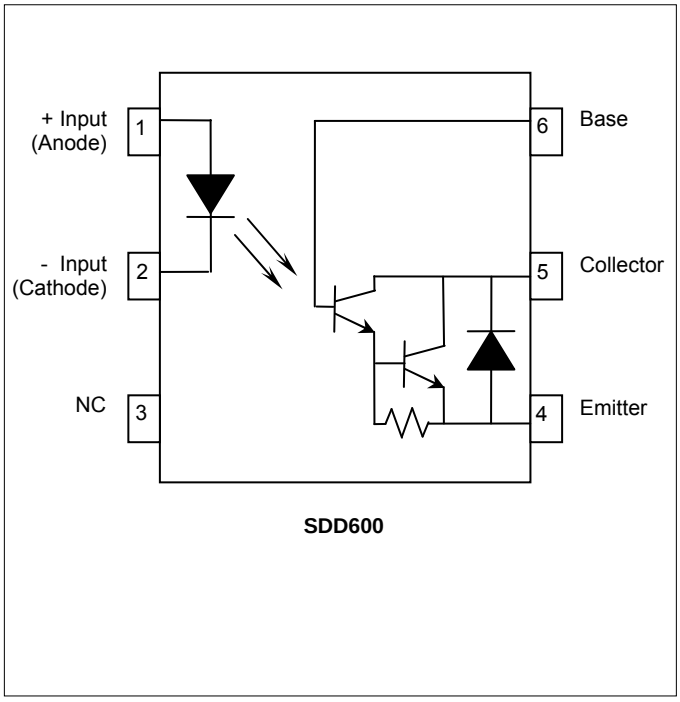
The SDD600 consists of a high voltage photo-Darlington transistor optically coupled to a light emitting diode. Optical coupling between the input IR LED and output photo-Darlington allows for high isolation levels while maintaining low-level DC signal control capability. The SDD600 provides an optically isolated method of controlling many interface applications such as telecommunications, industrial control, and instrumentation circuitry

The SDD600 comes standard in a miniature 6 pin DIP package.

Applications

- Office Automation Equipment
- System Appliances, Measuring Instruments
- Computer Terminals, PLCs
- Telecom / Datacom
- Home Appliances
- Digital Logic Inputs
- Fax / Modems
- Power Supplies

Schematic Diagram



SDD600

Features

- High Load Voltage (V_{CEO} = 300V MIN)
- High Current Transfer Ration (CTR: 600-9000%)
- Low input power consumption
- High stability
- High Isolation Voltage ($5000V_{RMS}$)
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL:	File # E201932
C-UL:	File # E201932
VDE:	License # 40011227

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature	-55 to +125°C
Operating Temperature	-40 to +100°C
Continuous Input Current	50mA
Transient Input Current	500mA
Reverse Input Control Voltage	6V
Input Power Dissipation	40mW
Total Power Dissipation	200mW
Solder Temperature – Wave (10sec)	260°C
Solder Temperature – IR Reflow (10sec)	260°C

Ordering Information

Part Number	Description
SDD600	6 pin DIP, (65/Tube)
SDD600-H	0.40" (10.16mm) Lead Spacing (VDE0884)
SDD600-S	6 pin SMD, (65/Tube)
SDD600-STR	6 pin SMD, Tape and Reel (2000/Reel)

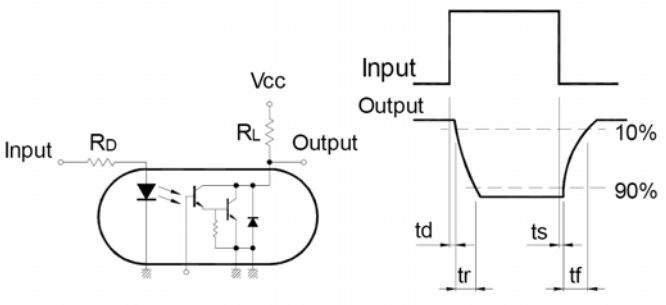
NOTE: Suffixes listed above are not included in marking on device for part number identification

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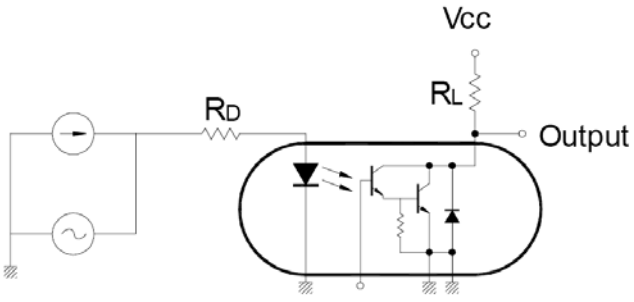
Electrical Characteristics, T_A = 25°C (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.2	1.4	V	I_F = 10mA
LED Reverse Voltage	BV_R	5	-	-	V	I_R = 10µA
Terminal Capacitance	C_t	-	30	250	pF	V=0, f=1KHz
Reverse Current	I_R	-	-	10	µA	V_R=4V
Output Specifications						
Collector-Emitter Voltage	V_{CEO}	300	-	-	V	I_C=10µA
Emitter-Collector Voltage	V_{COE}	0.1	-	-	V	I_E=10µA
Collector Dark Current	I_{CEO}	-	-	1	µA	V_{CE}=200V, I_F=0mA
Floating Capacitance	C_f	-	0.6	1.0	pF	V=0, f=1MHz
Cut-Off Frequency	f_C	1	7	-	kHz	V_{CE}=2V, I_C=20mA, R_L=100Ω, -3dB
Saturation Voltage	$V_{CE(sat)}$	-	-	1.2	V	I_F=20mA, I_C=100mA
Coupled Specifications						
Rise Time	T_R	-	100	300	µS	I_C=20mA, V_{CC}=2V, R_L=100Ω
Fall Time	T_F	-	20	100	µS	I_C=20mA, V_{CC}=2V, R_L=100Ω
Current Transfer Ratio	CTR	1000	4000	15000	%	I_F=1mA, V_{CE}=2V
Isolation Specifications						
Isolation Voltage	V_{ISO}	5000	-	-	V_{RMS}	RH ≤ 50%, t=1min
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	V_{I-O} = 500V_{DC}

Test Circuit: *Response Time*



Test Circuit: *Frequency Response*



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SDD600 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 1: *Forward Current (I_F) vs. Temperature (°C)*

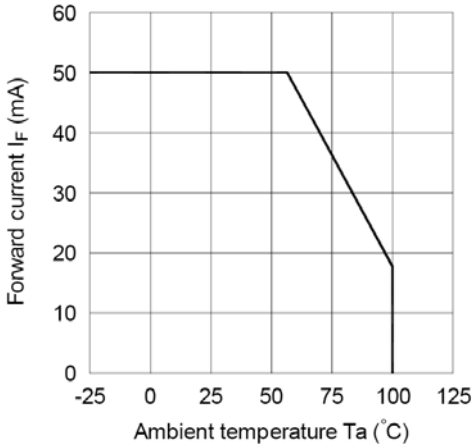


Figure 2: *Collector Power Dissipation (P_C) vs. Temperature (°C)*

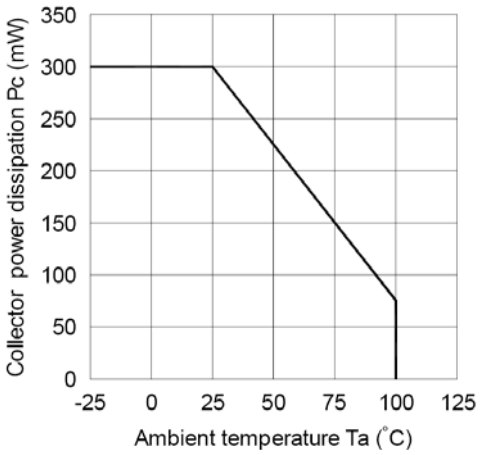


Figure 3: *Collector-Emitter Saturation Voltage ($V_{CE(SAT)}$) vs. Forward Current (I_F)*

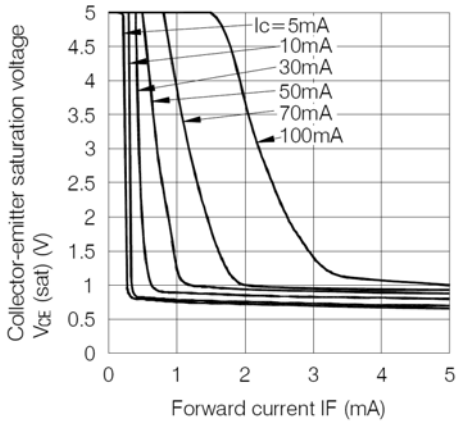


Figure 4: *Forward Current (I_F) vs. Forward Voltage (V_F)*

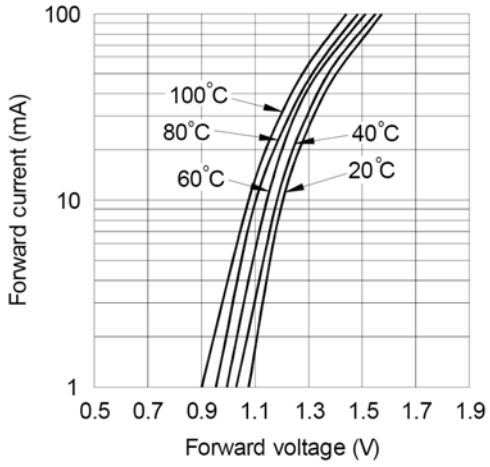


Figure 5: *Collector Current (I_C) vs. Collector-Emitter Voltage (V_{CE})*

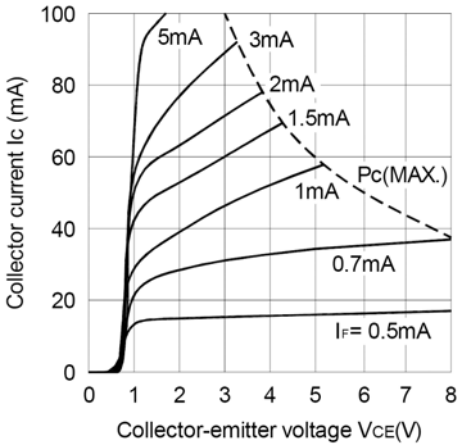
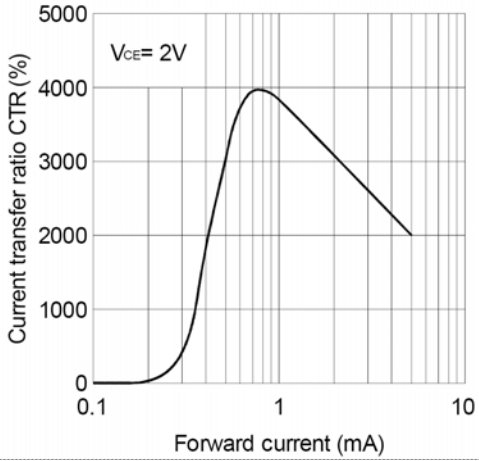


Figure 6: *Current Transfer Ratio (CTR) vs. Forward Current (I_F)*



SDD600 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 7: *Relative CTR (%) vs. Temperature (°C)*

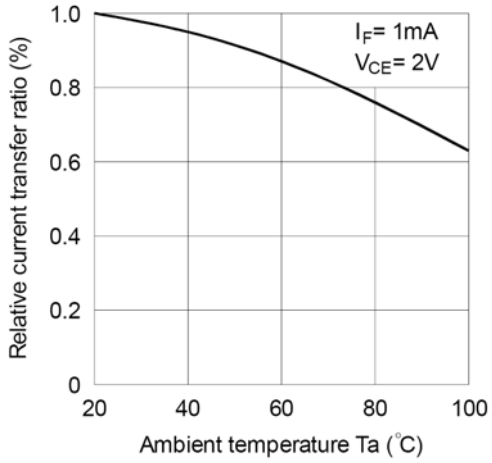


Figure 8: *Collector-Emitter Saturation Voltage ($V_{CE(SAT)}$) vs. Temperature (°C)*

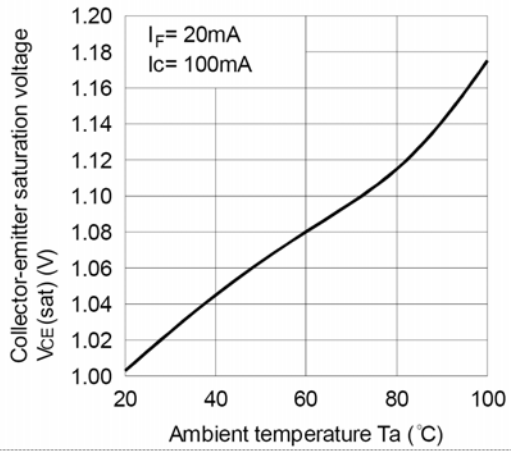


Figure 9: *Collector Dark Current (I_{CEO}) vs. Temperature (°C)*

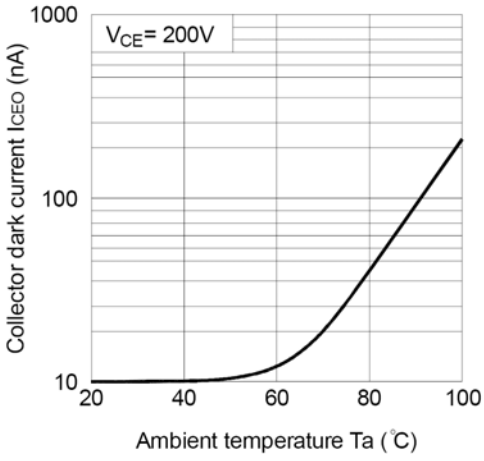


Figure 10: *Response Times vs. Load Resistance (R_L)*

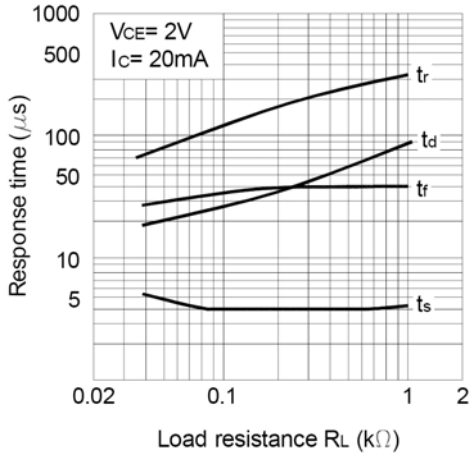
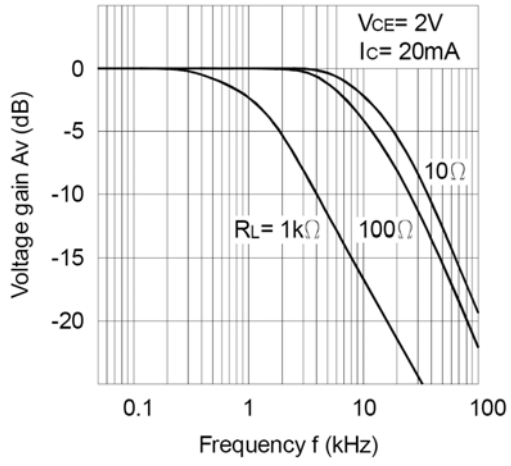


Figure 11: *Frequency Response Characteristics*

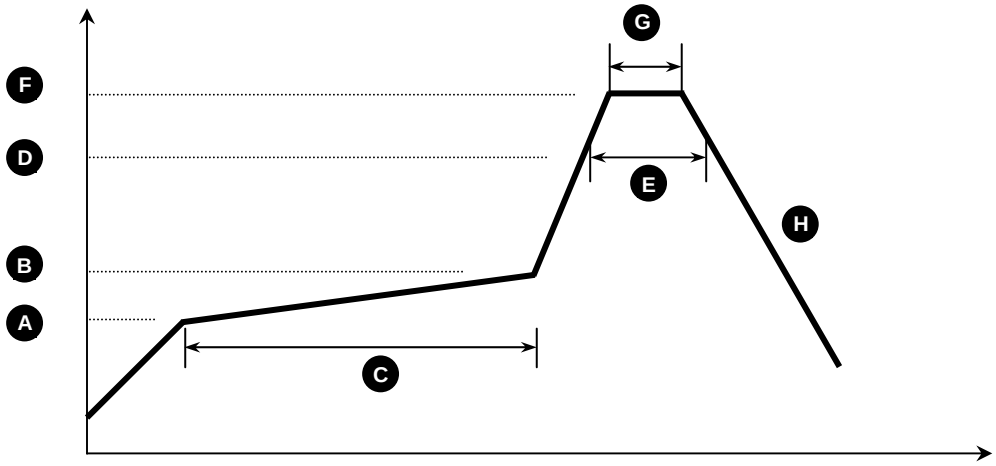


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SDD600 Solder Reflow Temperature Profile Recommendations

(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250ºC:



Process Step	Description	Parameter
A	Preheat Start Temperature (ºC)	150ºC
B	Preheat Finish Temperature (ºC)	180ºC
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (ºC)	230ºC
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (ºC)	260ºC
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (ºC/s)	<6ºC/s

(2) *Wave Solder:*

Maximum Temperature:	260ºC (at terminal)
Maximum Time:	10s
Pre-heating:	100 - 150ºC (30 - 90s)
Single Occurrence	

(3) *Hand Solder:*

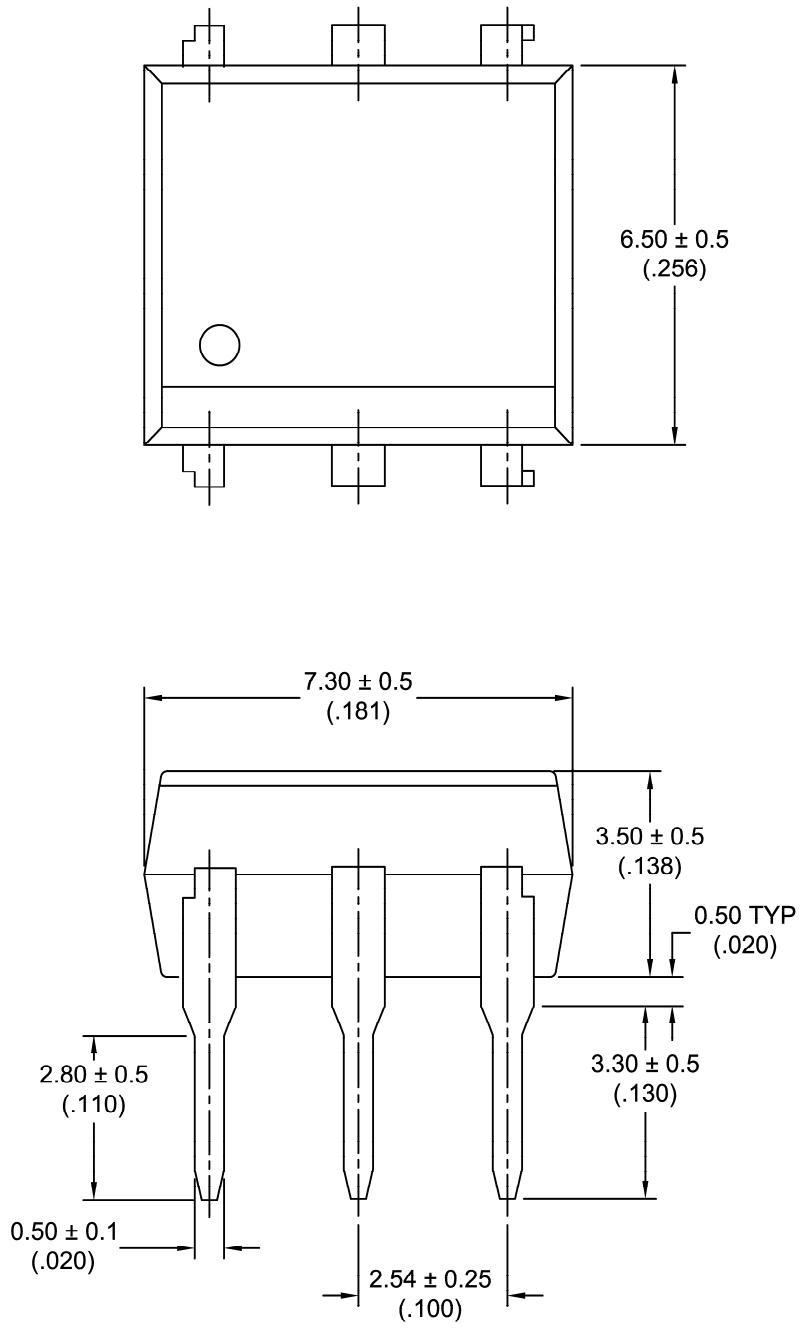
Maximum Temperature:	350ºC (at tip of soldering iron)
Maximum Time:	3s
Single Occurrence	

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SDD600 Package Dimensions

6 PIN DIP Package

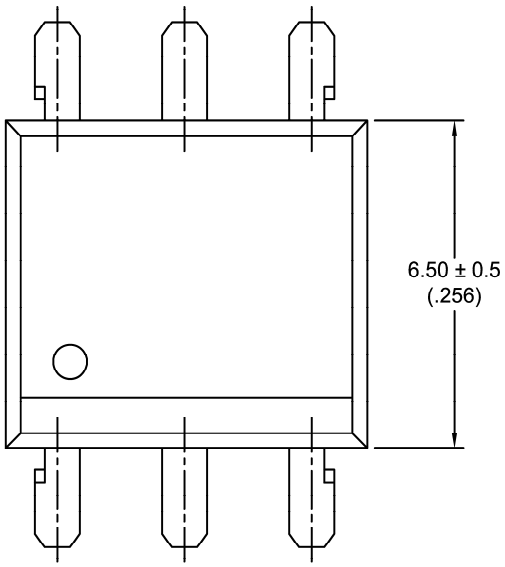
Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*

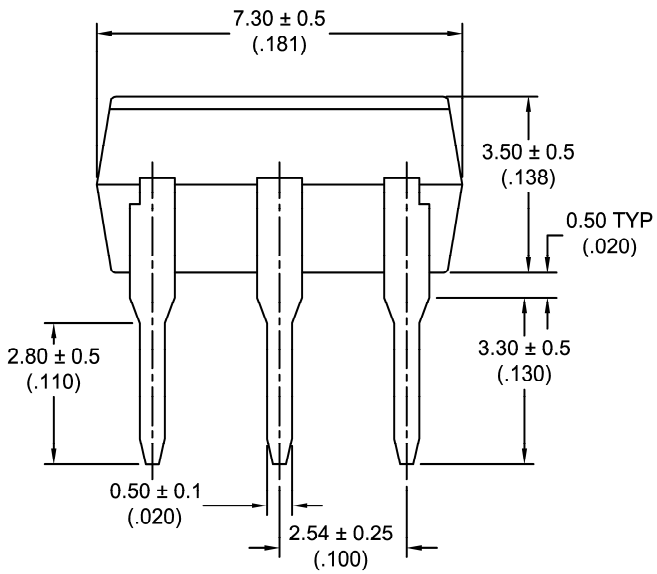


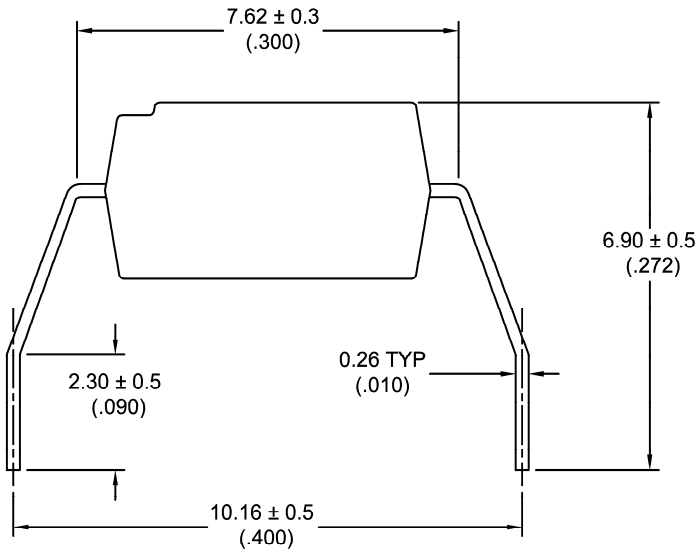
SDD600 Package Dimensions

6 PIN WIDE Lead Space Package (-H)

Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*





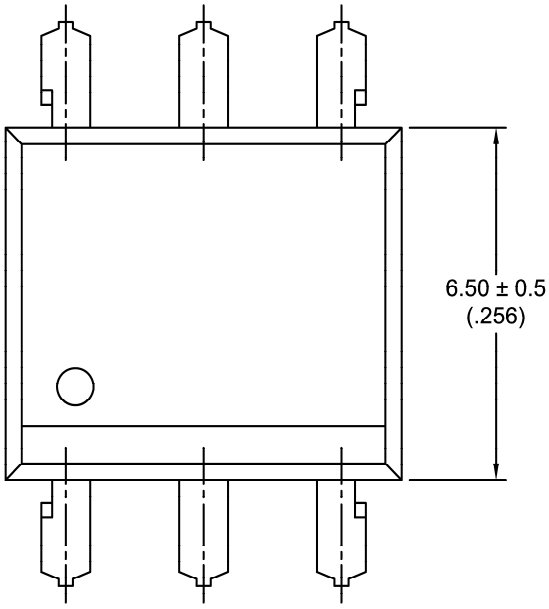


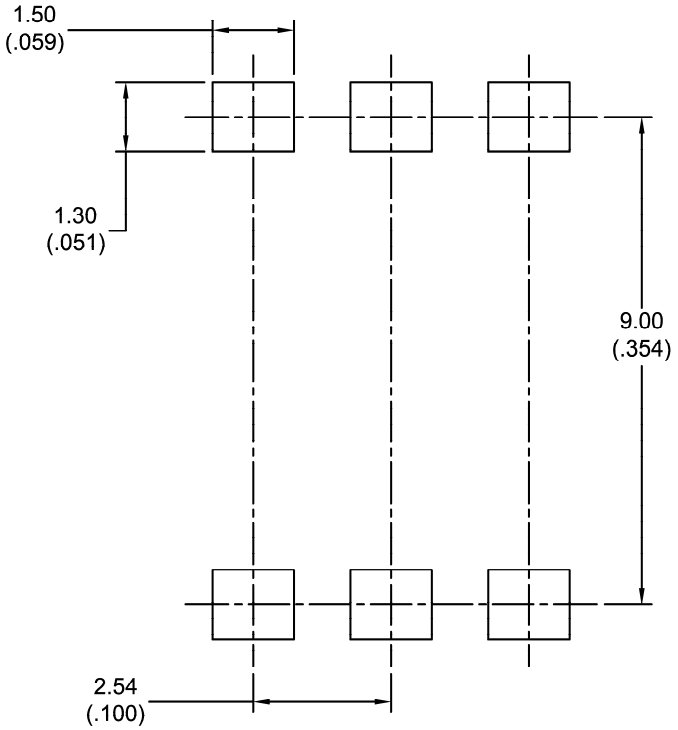
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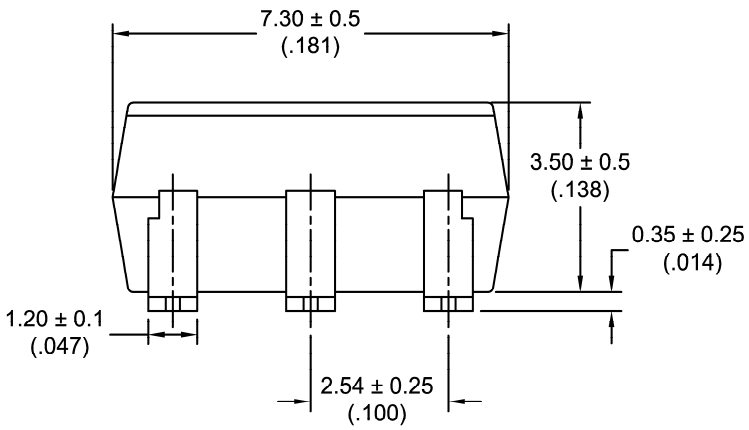
SDD600 Package Dimensions

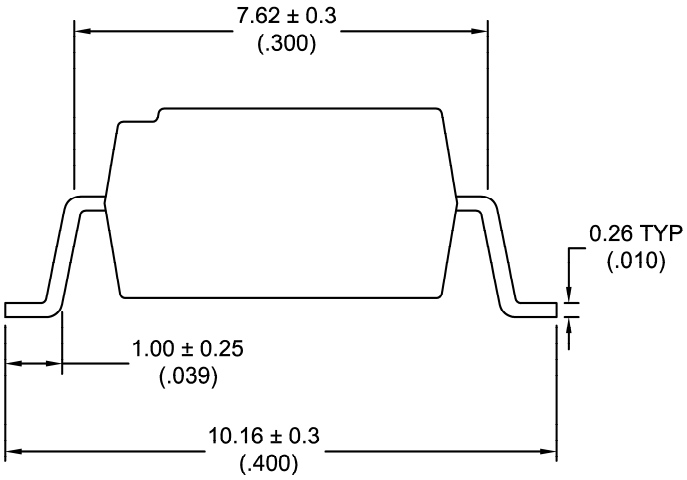
6 PIN SMD Surface Mount Package (-S)

Note: *All dimensions in millimeters [mm] with inches in parenthesis ()*





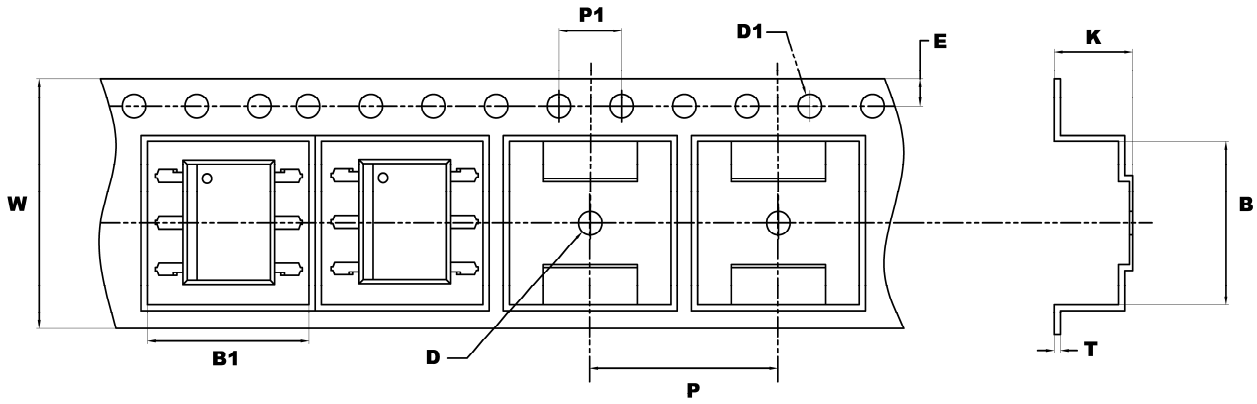




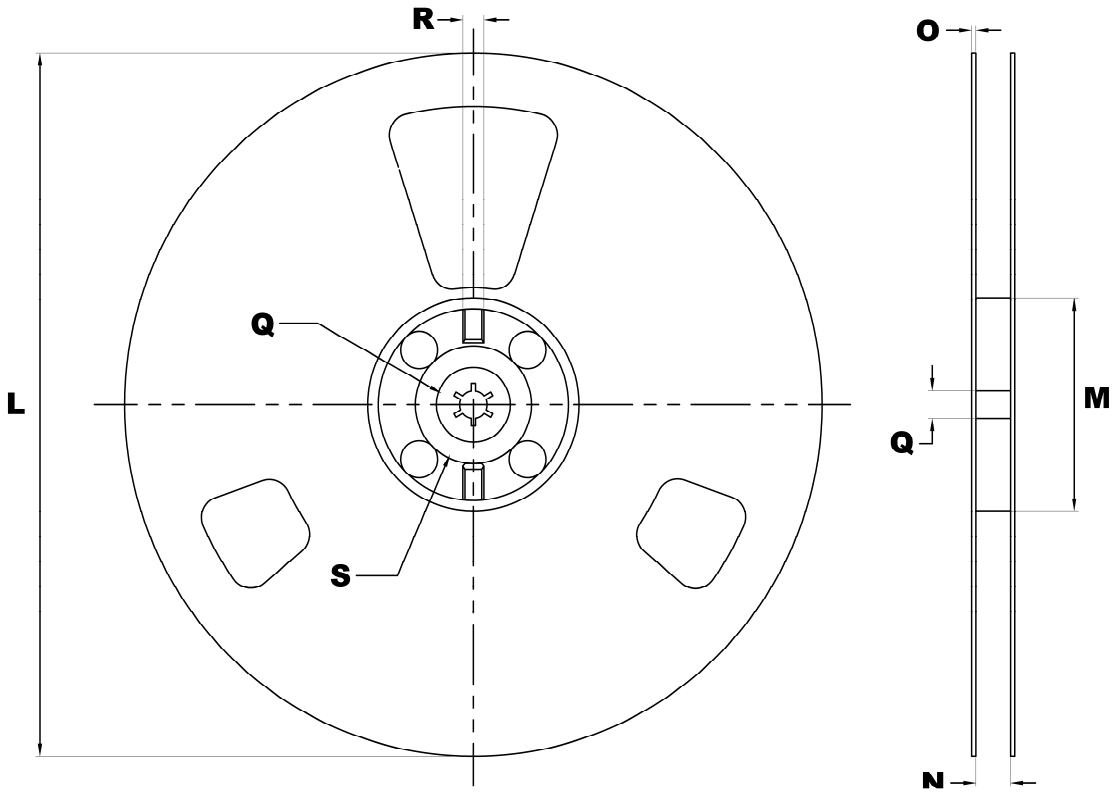
SDD600 Packaging Specifications

Tape & Reel Specifications (T&R)

Note: *All dimensions in millimeters [mm]*



B	B1	D	D1	E	K	P	P1	T	W
7.70±0.1	10.46±0.1	ø1.60±0.1	ø1.55±0.05	1.75±0.1	4.25±0.1	12.0±0.1	4.00±0.1	0.3±0.05	16±0.3



L	M	N	O	Q	R	S
330±2	101.6±1	16.4+0.2	2.0±0.2	R13±0.5	1.50±0.5	R10±1

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